D

TOP VIEW

SIDE VIEW

BOTTOM VIEW

еD

Α В

Ε

- A2

Α

C SEATING PLANE

0.03 C

0.05 | C | A | B |

26X ∅ b

еE

Ф



PIN A1 REFERENCE 2X 🗀

0.10

0.10 C

0.10 C

0.05 С

NOTE 3

WLCSP26, 2.388x2.233 CASE 567CY-01 **ISSUE A**

DATE 27 MAY 2011

NOTES:

- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

	MILLIMETERS		
DIM	MIN	MAX	
Α	0.84	1.00	
A1	0.17	0.23	
A2	0.72 REF		
b	0.24	0.29	
D	2.388 BSC		
E	2.233 BSC		
eD	0.252 BSC		
еE	0.310 BSC		

GENERIC MARKING DIAGRAM*



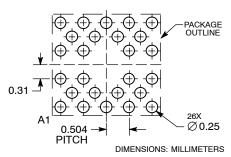
XXXXXX = Specific Device Code

= Assembly Location Α Υ

= Year WW = Work Week = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " •", may or may not be present.

RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

DESCRIPTION:	WLCSP26, 2.388X2.233		PAGE 1 OF 2
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ISSUE	REVISION	DATE
0	RELEASED FOR PRODUCTION. REQ. BY B. JENSEN.	02 NOV 2010
Α	CORRECTED PITCH IN SOLDER FOOTPRINT FROM 0.35 TO 0.31. REQ. BY C. CALAME.	27 MAY 2011

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